

# HD74LS279

## Quadruple $\bar{S}$ - $\bar{R}$ Latches

REJ03D0474-0400  
 Rev.4.00  
 May 10, 2006

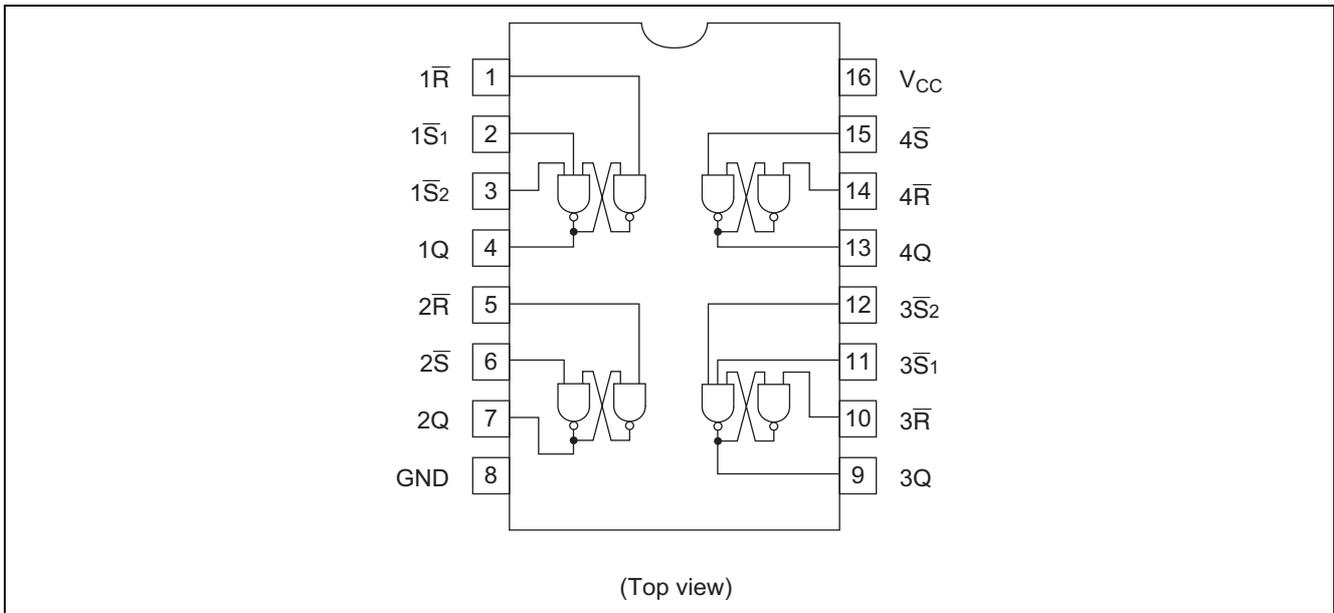
### Features

- Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LS279P	DILP-16 pin	PRDP0016AE-B (DP-16FV)	P	—
HD74LS279FPEL	SOP-16 pin (JEITA)	PRSP0016DH-B (FP-16DAV)	FP	EL (2,000 pcs/reel)

Note: Please consult the sales office for the above package availability.

### Pin Arrangement

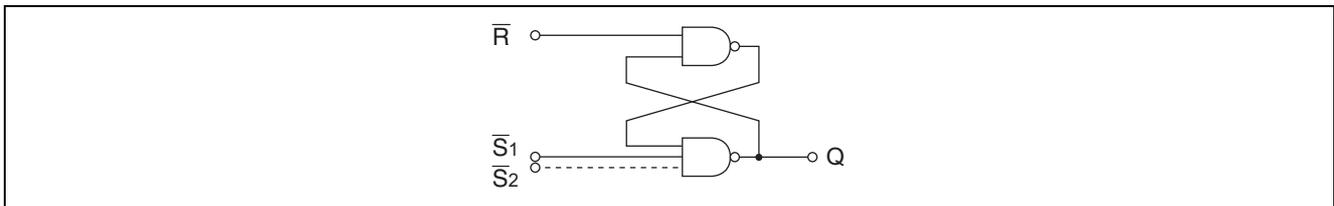


**Function Table**

Inputs		Output
$\bar{S}^{**}$	$\bar{R}$	Q
H	H	Q <sub>0</sub>
L	H	H
H	L	L
L	L	H*

- Notes: 1. H; high level, L; low level  
 2. Q<sub>0</sub>; The level of Q before the indicated input conditions were established.  
 3. \*; This output level is psodo stable; that is it may not persist when  $\bar{S}$  and  $\bar{R}$  inputs return to their inactive (high) level.  
 4. \*\*; For latches with double  $\bar{S}$  inputs; H; both  $\bar{S}$  inputs high, L; one or both  $\bar{S}$  inputs low.

**Block Diagram (1/4)**



**Absolute Maximum Ratings**

Item	Symbol	Ratings	Unit
Supply voltage	V <sub>CC</sub>	7	V
Input voltage	V <sub>IN</sub>	7	V
Power dissipation	P <sub>T</sub>	400	mW
Storage temperature	T <sub>stg</sub>	-65 to +150	°C

Note: Voltage value, unless otherwise noted, are with respect to network ground terminal.

**Recommended Operating Conditions**

Item	Symbol	Min	Typ	Max	Unit
Supply voltage	V <sub>CC</sub>	4.75	5.00	5.25	V
Output current	I <sub>OH</sub>	—	—	-400	μA
	I <sub>OL</sub>	—	—	8	mA
Operating temperature	T <sub>opr</sub>	-20	25	75	°C

## Electrical Characteristics

(Ta = -20 to +75 °C)

Item	Symbol	min.	typ.*	max.	Unit	Condition
Input voltage	V <sub>IH</sub>	2.0	—	—	V	
	V <sub>IL</sub>	—	—	0.8	V	
Output voltage	V <sub>OH</sub>	2.7	—	—	V	V <sub>CC</sub> = 4.75 V, V <sub>IH</sub> = 2 V, V <sub>IL</sub> = 0.8 V, I <sub>OH</sub> = -400 μA
	V <sub>OL</sub>	—	—	0.4	V	V <sub>CC</sub> = 4.75 V, V <sub>IH</sub> = 2 V, V <sub>IL</sub> = 0.8 V
—		—	0.5			
Input current	I <sub>IH</sub>	—	—	20	μA	V <sub>CC</sub> = 5.25 V, V <sub>I</sub> = 2.7 V
	I <sub>IL</sub>	—	—	-0.4	mA	V <sub>CC</sub> = 5.25 V, V <sub>I</sub> = 0.4 V
	I <sub>I</sub>	—	—	0.1	mA	V <sub>CC</sub> = 5.25 V, V <sub>I</sub> = 7 V
Short-circuit output current	I <sub>OS</sub>	-20	—	-100	mA	V <sub>CC</sub> = 5.25 V
Supply current**	I <sub>CC</sub>	—	3.8	7	mA	V <sub>CC</sub> = 5.25 V
Input clamp voltage	V <sub>IK</sub>	—	—	-1.5	V	V <sub>CC</sub> = 4.75 V, I <sub>IN</sub> = -18 mA

Notes: \* V<sub>CC</sub> = 5 V, Ta = 25°C\*\* I<sub>CC</sub> is measured with all  $\bar{R}$  inputs grounded, all  $\bar{S}$  inputs at 4.5 V, and all outputs open.

## Switching Characteristics

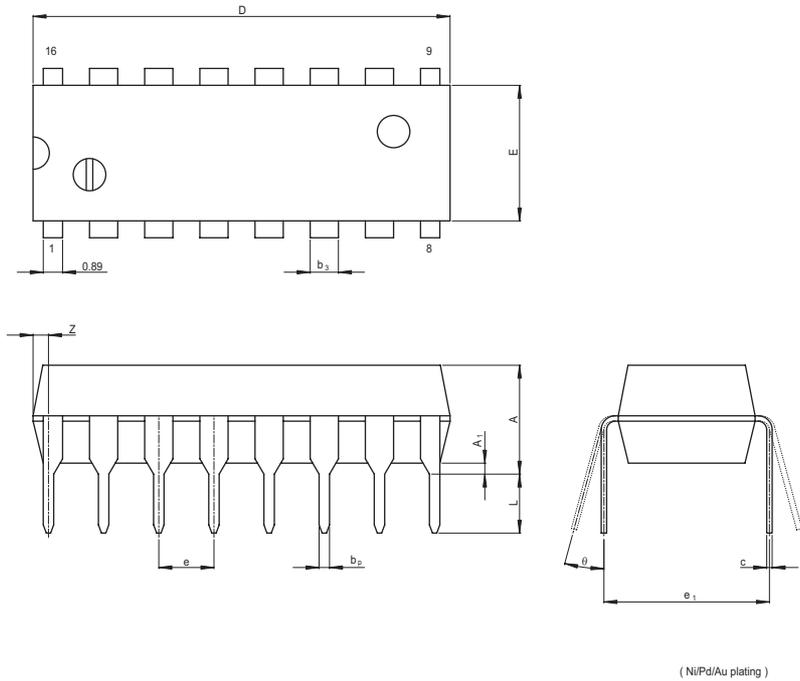
(V<sub>CC</sub> = 5 V, Ta = 25°C)

Item	Symbol	Inputs	Output	min.	typ.	max.	Unit	Condition
Propagation delay time	t <sub>PLH</sub>	$\bar{S}$	Q	—	12	22	ns	C <sub>L</sub> = 15 pF, R <sub>L</sub> = 2 kΩ
	t <sub>PHL</sub>			—	13	21		
	t <sub>PHL</sub>	$\bar{R}$		—	15	27		

Note: Refer to Test Circuit and Waveform of the Common Item "TTL Common Matter (Document No.: REJ27D0005-0100)".

Package Dimensions

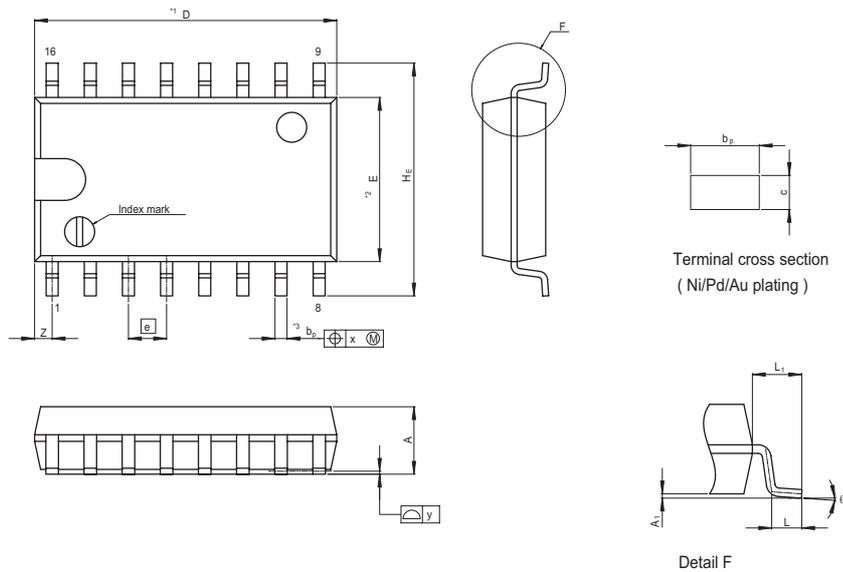
JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-DIP16-6.3x19.2-2.54	PRDP0016AE-B	DP-16FV	1.05g



Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
e <sub>1</sub>	—	7.62	—
D	—	19.2	20.32
E	—	6.3	7.4
A	—	—	5.06
A <sub>1</sub>	0.51	—	—
b <sub>p</sub>	0.40	0.48	0.56
b <sub>3</sub>	—	1.30	—
c	0.19	0.25	0.31
θ	0°	—	15°
e	2.29	2.54	2.79
Z	—	—	1.12
L	2.54	—	—

( Ni/Pd/Au plating )

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-SOP16-5.5x10.06-1.27	PRSP0016DH-B	FP-16DAV	0.24g



NOTE:  
 1. DIMENSIONS\*\*1 (Nom)\*\*AND\*\*2\* DO NOT INCLUDE MOLD FLASH.  
 2. DIMENSION\*\*3\*DOES NOT INCLUDE TRIM OFFSET.

Terminal cross section  
( Ni/Pd/Au plating )

Detail F

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	10.06	10.5
E	—	5.50	—
A <sub>2</sub>	—	—	—
A <sub>1</sub>	0.00	0.10	0.20
A	—	—	2.20
b <sub>p</sub>	0.34	0.40	0.46
b <sub>1</sub>	—	—	—
c	0.15	0.20	0.25
c <sub>1</sub>	—	—	—
θ	0°	—	8°
HE	7.50	7.80	8.00
Ⓜ	—	1.27	—
x	—	—	0.12
y	—	—	0.15
Z	—	—	0.80
L	0.50	0.70	0.90
L <sub>1</sub>	—	1.15	—

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